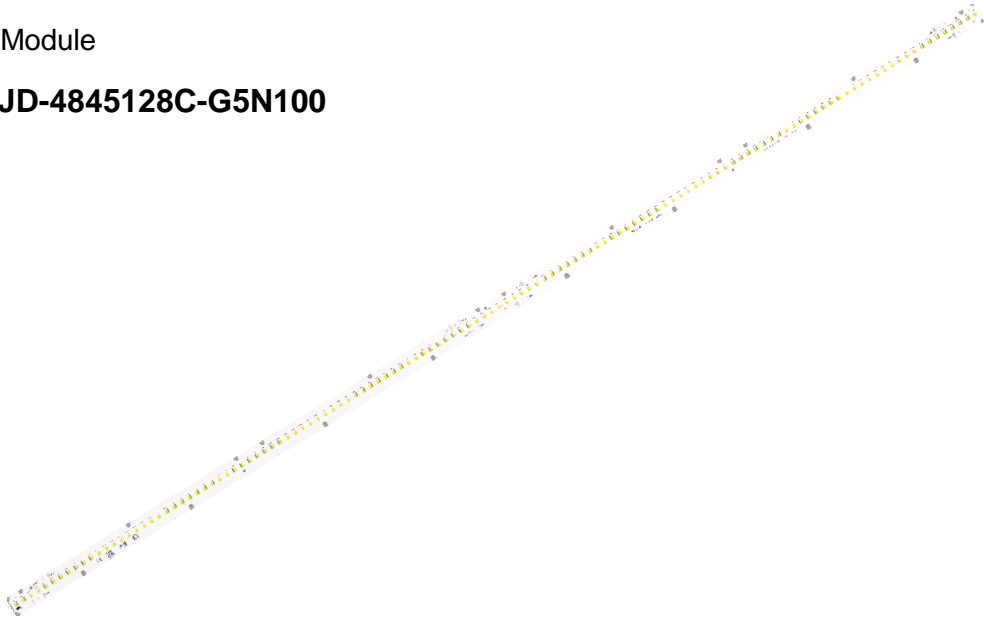


DC Module

**SMJD-4845128C-G5N100**



## Product Brief

### Description

- Multiple CCT is optional
- Modular design concept, easily expand to multitude application
- Poke-in connector in built
- Zhaga book 7 compliant LED module
- Cutable module

### Features and Benefits

- High Efficacy
- Long Life Time
- Simple BOM
- Lead Free Product
- RoHS Compliant

### Key Applications

- Linear lighting
- Decorative lighting
- Troffer

## Product Code Information

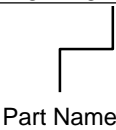
**Table 1. Order Code**

CCT	CRI	Lens type	Order Code
6500	80	-	SMJD-4845128C-G5N100I02A038ALL
5700		-	SMJD-4845128C-G5N100I15B038ALL
5000		-	SMJD-4845128C-G5N100I20C038ALL
4000		-	SMJD-4845128C-G5N100I20E038ALL
3500		-	SMJD-4845128C-G5N100I02F038ALL
3000		-	SMJD-4845128C-G5N100H75G038ALL
2700		-	SMJD-4845128C-G5N100H57H038ALL
6500	90	-	SMJD-4845128C-G5N100G76A039ALL
5700		-	SMJD-4845128C-G5N100G76B039ALL
5000		-	SMJD-4845128C-G5N100G99C039ALL
4000		-	SMJD-4845128C-G5N100G99E039ALL
3500		-	SMJD-4845128C-G5N100G76F039ALL
3000		-	SMJD-4845128C-G5N100G50G039ALL
2700		-	SMJD-4845128C-G5N100G41H039ALL


**Notes:**

(1) Order code include 18D(Part Name) + 2D(lens Type) + 10D(Characteristics)


**SMJD-4845128C-G5N1**   **00**   **I20E038All**



Part Name



Lens Type



Characteristics

---

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## Performance Characteristics

**Table2-1. Electro Optical Characteristics,  $I_F=1000\text{mA}$ ,  $T_c=50^\circ\text{C}$  for Ra80**

Parameter	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Luminous Flux	$\Phi_V^{[2]}$	7460	8020	-	Lm	A rank
		7580	8150	-		B rank
		7630	8200	-		C rank
		7630	8200	-		E rank
		7460	8020	-		F rank
		7210	7750	-		G rank
		7040	7570	-		H rank
Luminous Efficiency	LPW	-	179	-	Lm/W	A rank
		-	182	-		B rank
		-	183	-		C rank
		-	183	-		E rank
		-	179	-		F rank
		-	173	-		G rank
		-	169	-		H rank
Correlated Color Temperature <sup>[3]</sup>	CCT	6000	6500	7000	K	A rank
		5300	5700	6000		B rank
		4700	5000	5300		C rank
		3700	4000	4200		E rank
		3200	3500	3700		F rank
		2900	3000	3200		G rank
		2600	2700	2900		H rank
CRI	Ra	80	-	-	-	
Color Consistency		-	-	3	SDCM	
Input Voltage	$V_{in}$	42.8	44.8	46.8	Vdc	
Forward Current	$I_F$		1000		mA	
Power Consumption	P		44.8		W	
Viewing Angle	$2\theta_{1/2}$		120		deg.	

**Notes :**

- 1) The above data were tested at  $T_c=50^\circ\text{C}$ .
- 2)  $\Phi_V$  is the total luminous flux output measured with an integrated sphere, the tolerance is 7% .
- 3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- 4) To use the module properly, recommend to drive the module by a Constant Current Source (CCS). But the Maximum output voltage of the CCS should be limited by referring this datasheet.

## Performance Characteristics

**Table2-2. Electro Optical Characteristics,  $I_F=1000\text{mA}$ ,  $T_c=50^\circ\text{C}$  for Ra90**

Parameter	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Luminous Flux	$\Phi_V^{[2]}$	6290	6760	-	Lm	A rank
		6290	6760	-		B rank
		6500	6990	-		C rank
		6500	6990	-		E rank
		6290	6760	-		F rank
		6050	6500	-		G rank
		5960	6410	-		H rank
Luminous Efficiency	LPW	-	151	-	Lm/W	A rank
		-	151	-		B rank
		-	156	-		C rank
		-	156	-		E rank
		-	151	-		F rank
		-	145	-		G rank
		-	143	-		H rank
Correlated Color Temperature <sup>[3]</sup>	CCT	6000	6500	7000	K	A rank
		5300	5700	6000		B rank
		4700	5000	5300		C rank
		3700	4000	4200		E rank
		3200	3500	3700		F rank
		2900	3000	3200		G rank
		2600	2700	2900		H rank
CRI	Ra	90	-	-	-	
Color Consistency		-	-	3	SDCM	
Input Voltage	$V_{in}$	42.8	44.8	46.8	Vdc	
Forward Current	$I_F$		1000		mA	
Power Consumption	P		44.8		W	
Viewing Angle	$2\Theta_{1/2}$		120		deg.	

**Notes :**

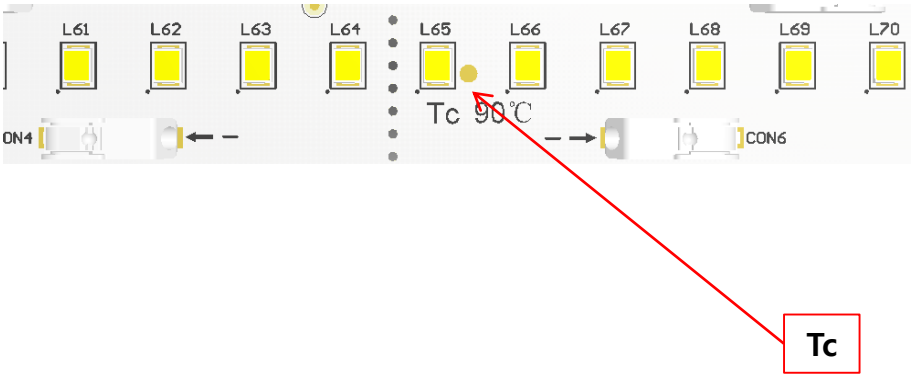
- 1) The above data were tested at  $T_c=50^\circ\text{C}$ .
- 2)  $\Phi_V$  is the total luminous flux output measured with an integrated sphere, the tolerance is 7% .
- 3) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- 4) To use the module properly, recommend to drive the module by a Constant Current Source (CCS). But the Maximum output voltage of the CCS should be limited by referring this datasheet.

# Absolute Maximum Ratings

Table 3. Absolute Maximum Ratings,  $T_c=50^{\circ}\text{C}$  <sup>(1)</sup>

Parameter	Symbol	Unit	Value	Remark
Power Consumption	P	W	77.8	$P_{Typ.}=44.8\text{W}$
Driving Current <sup>(2)</sup>	$I_F$	mA	1680	$I_{F\_Typ.}=1000\text{mA}$
Operating Temperature <sup>(3)</sup>	$T_c$	$^{\circ}\text{C}$	- 40 ~ 90	Reference point
Storage Temperature	$T_{stg}$	$^{\circ}\text{C}$	- 40 ~ 100	With no power
ESD Sensitivity	-	KV	$\pm 8$	IEC Air
			$\pm 4$	HBM

ILLUSTRATION 1: How to predict components temperature <sup>(4)</sup>



**Notes :**

- (1) All guarantee are based on the Absolute Maximum Ratings listed.
- (2) Please use a Constant Current Source (CCS) to drive the module, the typical  $V_F$  of module is around 44.8VDC and  $V_{F\_MAX}$  is around 46.8VDC, respectively.
- (3) Operating temperature was tested at the assigned  $T_c$  point on the PCB.
- (4) To ensure the module works properly, DO NOT let the  $T_c$  upper than 90  $^{\circ}\text{C}$ ;

## Relative Spectral Distribution

Fig 1. Relative Spectral Distribution vs. Wavelength Characteristic

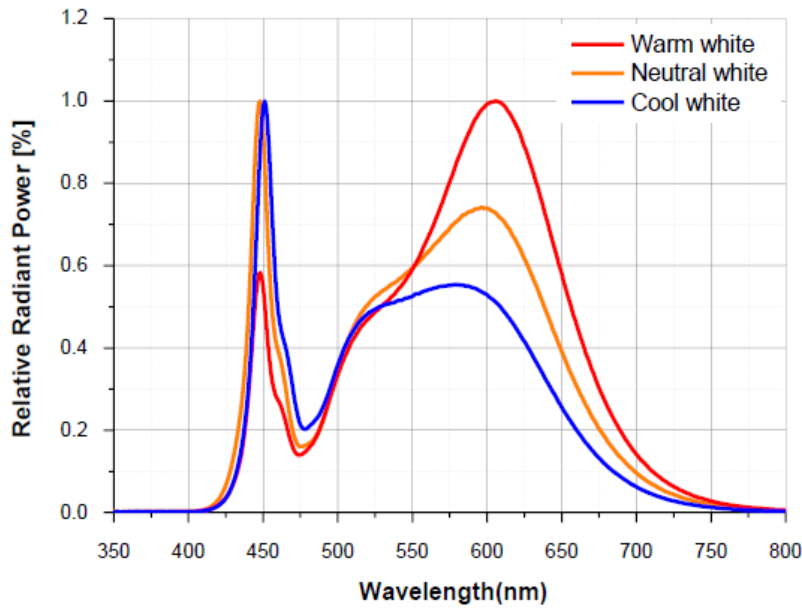
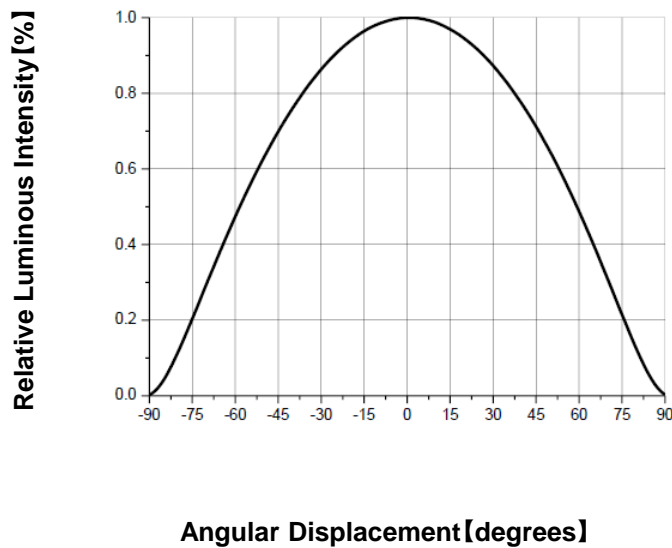


Fig 2. Typical Spatial Distribution



## Relative Spectral Distribution

Fig 3. Flux and Efficacy vs. Temperature at T<sub>c</sub>(at I<sub>F</sub>=1000mA)

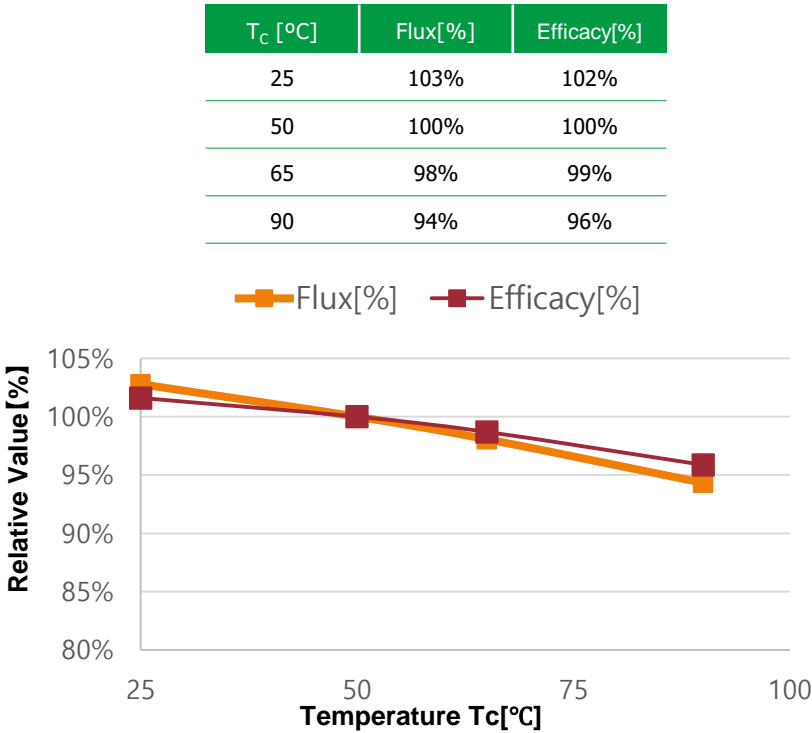
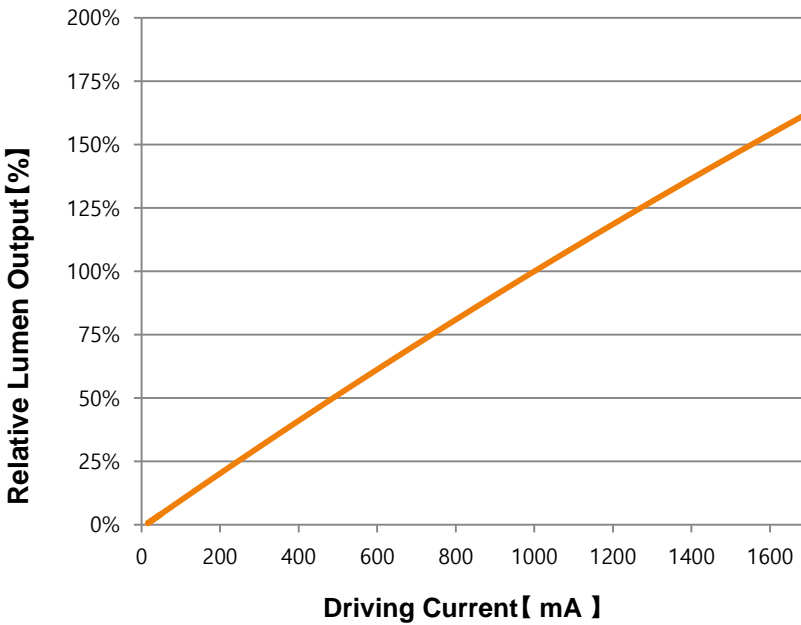
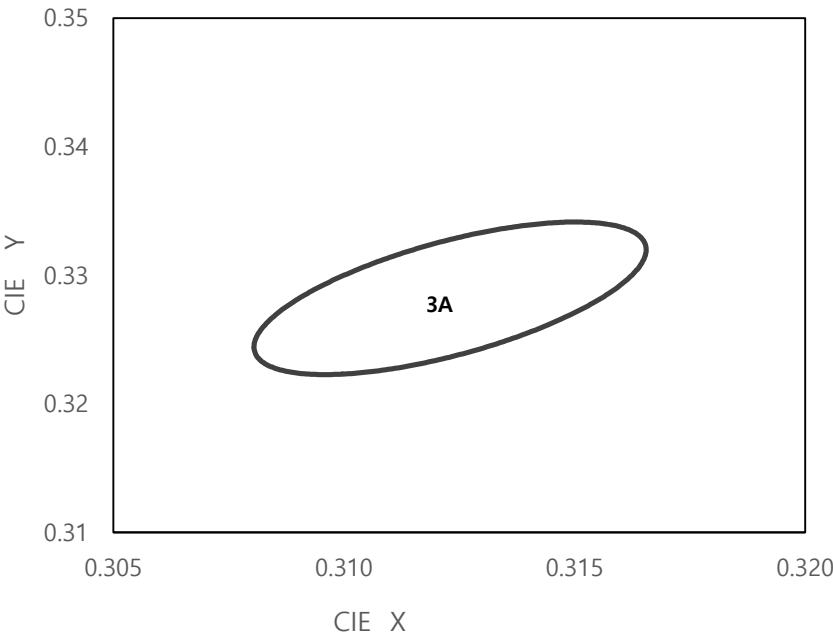


Fig 4. Forward Current vs. Relative Luminous Flux, T<sub>c</sub>=50°C



## Color Bin Structure

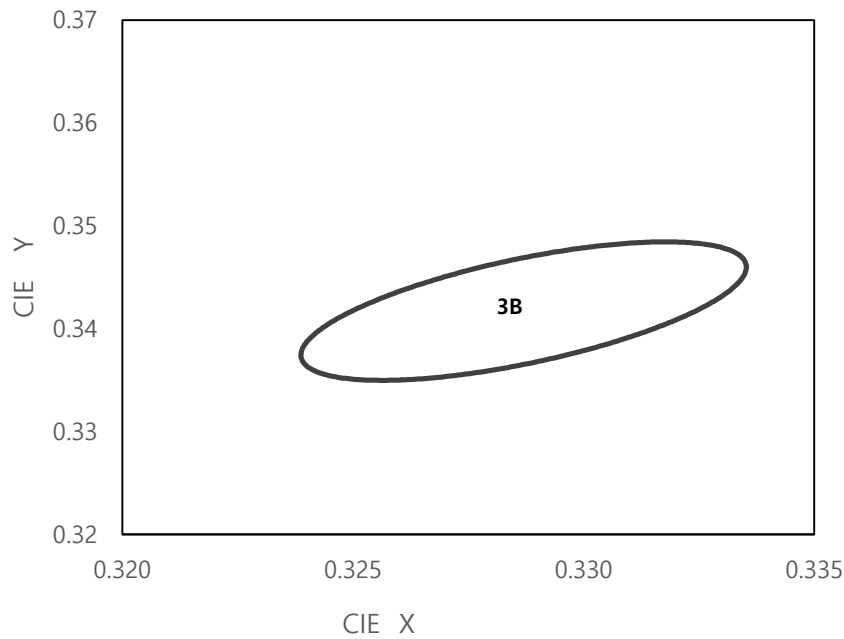
Fig 5. CIE Chromaticity Diagram



3A(3.0step)		
Center Point	0.3123	0.3282
Major Axis a	0.0067	
Minor Axis b	0.0029	
Ellipse Rotation Angle	59	

## Color Bin Structure

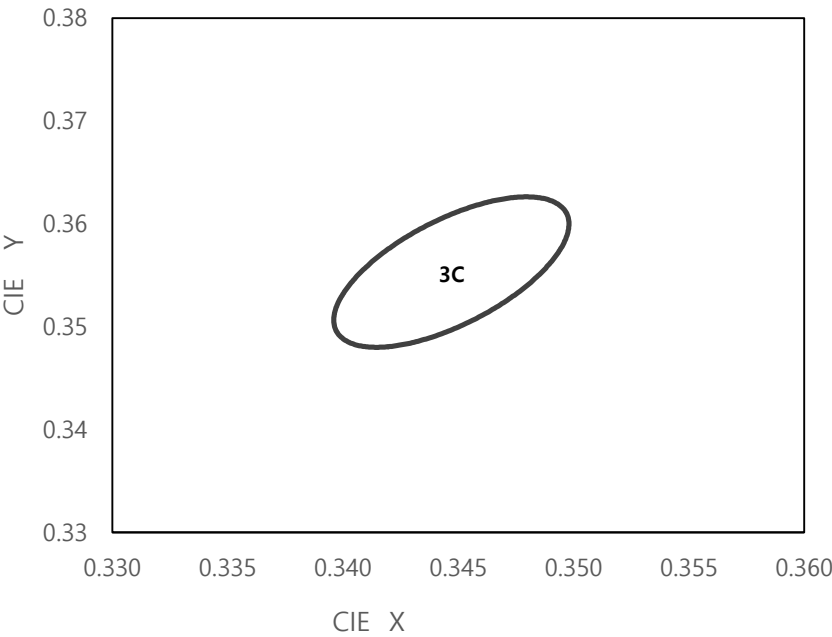
Fig 6. CIE Chromaticity Diagram



3B(3.0step)		
Center Point	0.3287	0.3417
Major Axis a	0.0076	
Minor Axis b	0.0033	
Ellipse Rotation Angle	59	

# Color Bin Structure

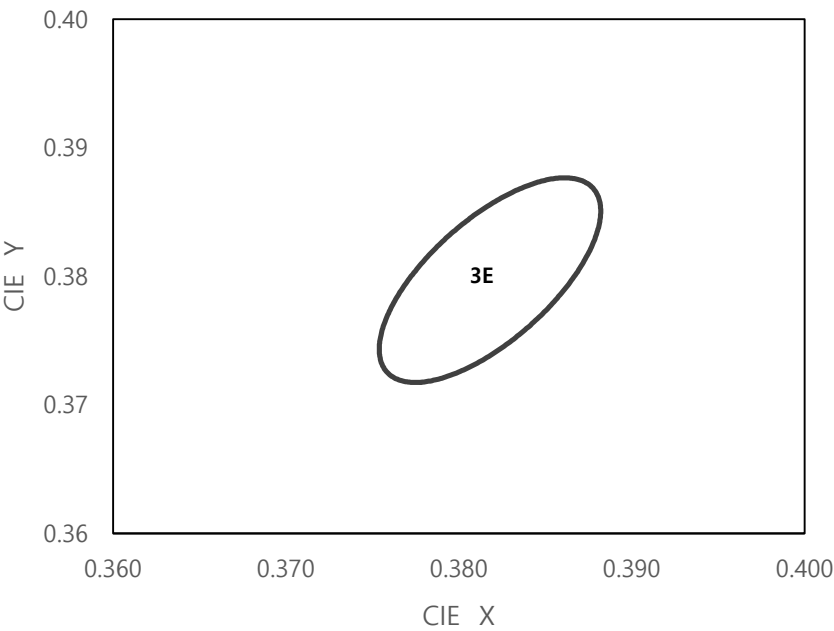
Fig 7. CIE Chromaticity Diagram



3C(3.0step)		
Center Point	0.3447	0.3553
Major Axis a	0.0082	
Minor Axis b	0.0035	
Ellipse Rotation Angle	60	

## Color Bin Structure

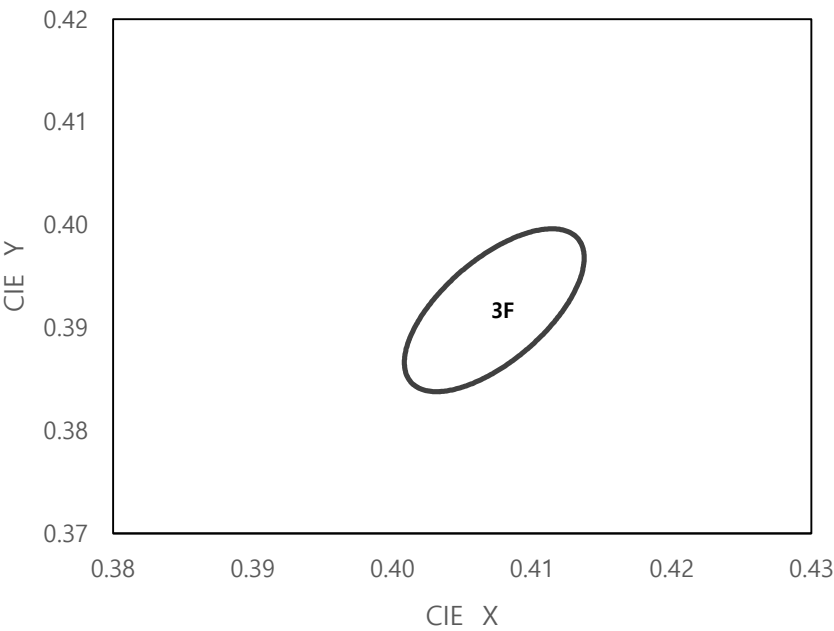
Fig 8. CIE Chromaticity Diagram



3E(3.0step)		
Center Point	0.3818	0.3797
Major Axis a	0.0094	
Minor Axis b	0.004	
Ellipse Rotation Angle	54	

# Color Bin Structure

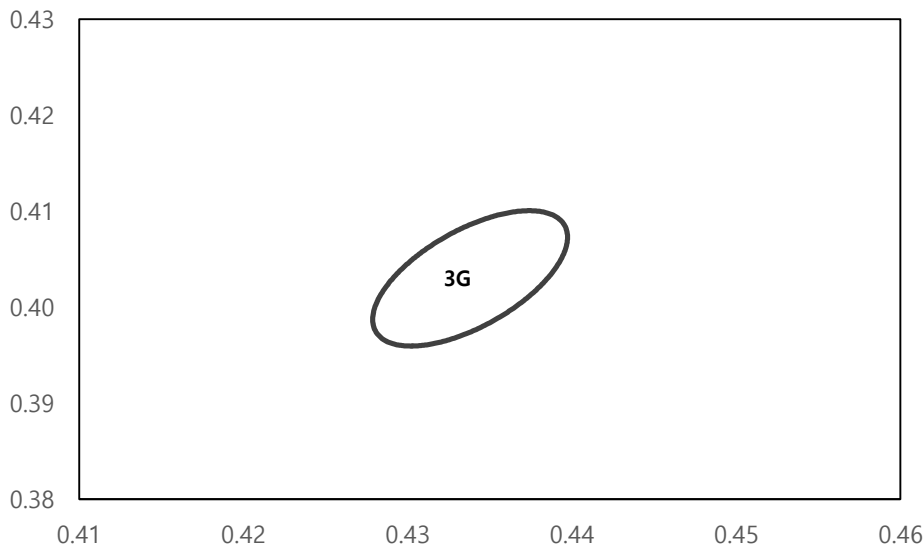
Fig 9. CIE Chromaticity Diagram



3F(3.0step)		
Center Point	0.4073	0.3917
Major Axis a	0.0093	
Minor Axis b	0.0042	
Ellipse Rotation Angle	54	

## Color Bin Structure

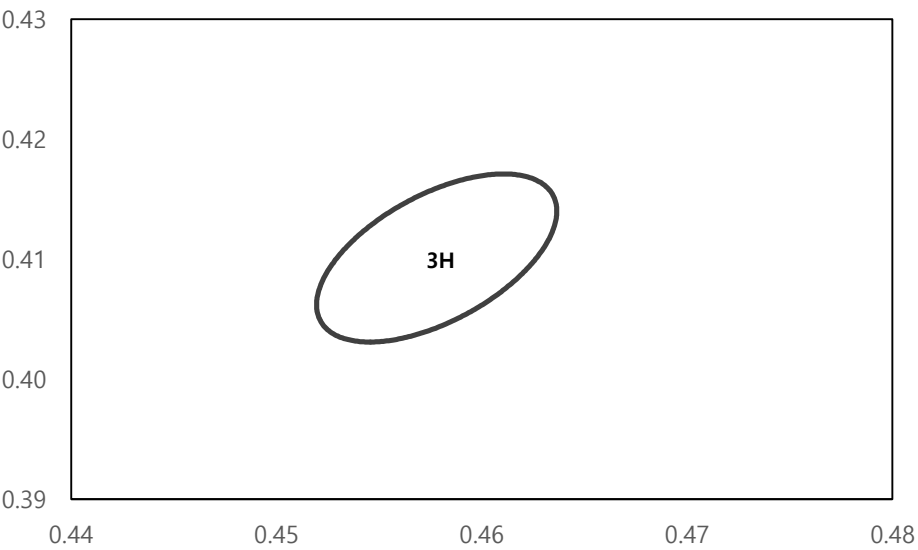
Fig 10. CIE Chromaticity Diagram



3G(3.0step)		
Center Point	0.4338	0.403
Major Axis a	0.0083	
Minor Axis b	0.004	
Ellipse Rotation Angle	53	

Color Bin Structure

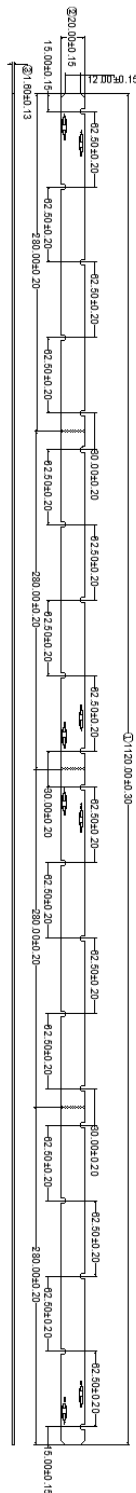
Fig 11. CIE Chromaticity Diagram



3H(3.0step)		
Center Point	0.4578	0.4101
Major Axis a	0.0081	
Minor Axis b	0.0042	
Ellipse Rotation Angle	54	

## Mechanical Dimensions

**Fig 12. PCBA Drawing**

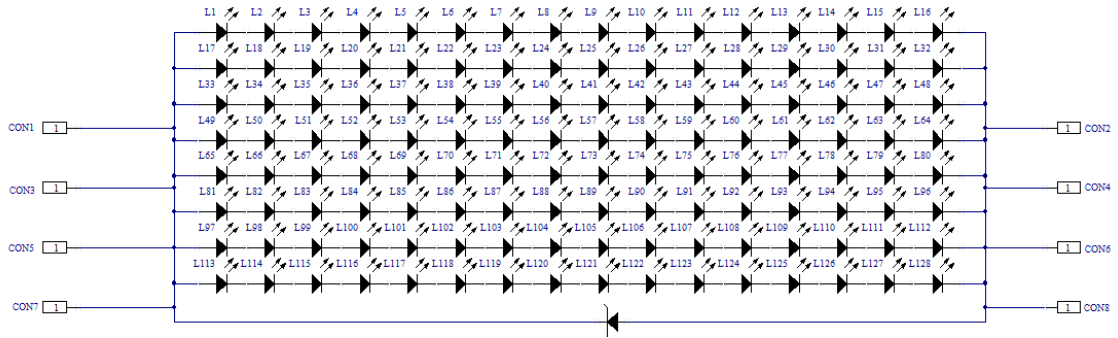


**Notes :**

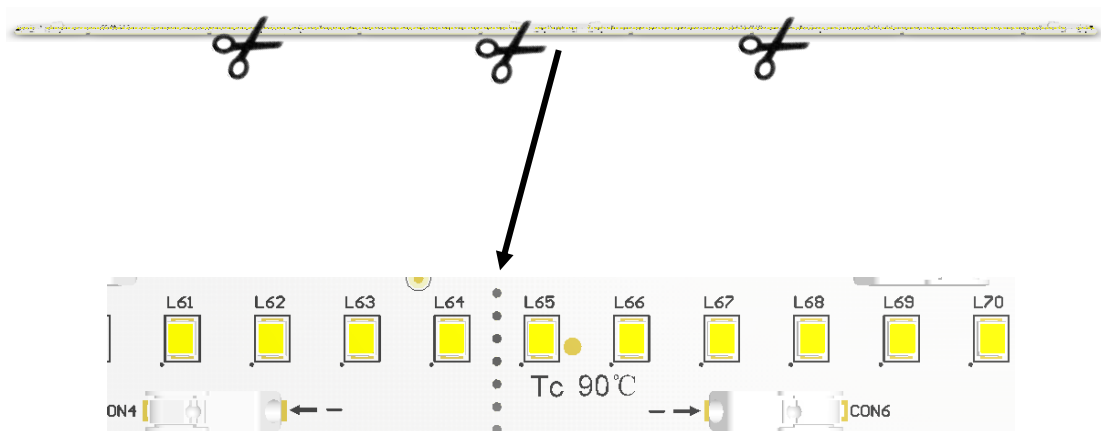
- (1) All dimensions are in millimeters.
- (2) Scale : None
- (3) Module thickness :  $6.2 \pm 0.1$

## Circuit Drawing

Fig 13. Circuit Drawing



## Application Guide



**Cuttable Module**

- \* Please use antistatic gloves or other ESD protection methods when handling this cuttable board to prevent ESD damage and contamination of LEDs.
- \* Customers should use proper tools and avoid using their hands when separating this cuttable board. Bending PCB and touch the LED is not allowed to separate the board.
- \* Customer should consider maintaining the withstand voltage spec in case of cutting the board.
- \* If customers do not follow the above guidelines regarding handling, we will not be responsible for any quality issue.
- \* When the insulation layer exposed after cutting the PCB, customers should consider for protecting insulation layer for any electrical damage.
- \* Please consider the creepage and clearance distance at the end product, including using plastic screws and/or tapes.

## Terminals

Actuation type	Push-in , Push-button
Solid conductor	0.2 ... 0.75 mm <sup>2</sup> / 24 ... 18 AWG
Fine-stranded conductor	0.2 ... 0.75 mm <sup>2</sup> / 24 ... 18 AWG
Fine-stranded conductor; with insulated ferrule	0.25 ... 0.34 mm <sup>2</sup>
Fine-stranded conductor; with uninsulated ferrule	0.25 ... 0.34 mm <sup>2</sup>
Strip length	7 ... 9 mm / 0.28 ... 0.35 inch
Conductor connection direction to PCB	0 °
Pole No.	1

## Certification

Item	Compliant to	Remark
Certification	UL/cUL	E315508

# Product Nomenclature

Product Name Rule:

S M J D   -   48   45   128   C   -   G5   N1   00

①                      ②                      ③                      ④                      ⑤                      ⑥                      ⑦                      ⑧

①: SMJD – Seoul DC Module  
 ② ~ ⑧: Refer to below table

Voltage				Power				LED Qty.						LED Type		Customer (Free)		FREE		Lens	
②				③				④						⑤		⑥		⑦		⑧	
4		8		9		0		2		5		6		C		G5		N1		00	
0	0	0	0	0	0	0	0	0	0	0	0	0	0	C	3528	G5	Internal code	N1	version	00	No Lens
1	10V	1	1V	1	10W	1	1W	1	100EA	1	10EA	1	1EA								
2	20V	2	2V	2	20W	2	2W	2	200EA	2	20EA	2	2EA								
3	30V	3	3V	3	30W	3	3W	3	300EA	3	30EA	3	3EA								
... ...		... ...		... ...		... ...		... ...		... ...		... ...									
9	90V	9	9V	9	90W	9	9W	9	900EA	9	90EA	9	9EA								
A	100V			A	100W			A	1000EA												
B	110V			B	110W																
... ...				... ...																	
Z	350V			Z	350W																

Comments Rule:

( 00   WN   80 )

A                      B                      C

Lens Type		CCT		CRI	
A		B		C	
00		W0		80	
00	No lens	W0	6500K	80	CRI80
			5700K	90	CRI90
			5000K		
		WN	4000K		
		WW	3500K		
			3000K		
			2700K		

# Product Nomenclature

Characteristics Rule:

I20

E03

8

All

A

B

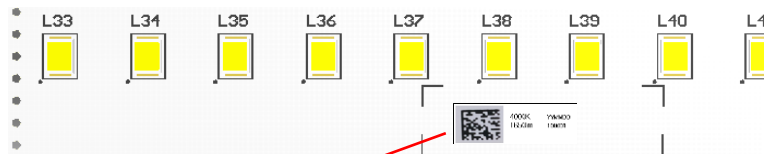
C

D

Flux bin		CCT bin		CRI bin		VF Bin <sup>(1)</sup>	
A		B		C		D	
I20		E03		8		ALL	
I02	8020 lm	A03	6500K 3-step	8	CRI80	ALL	VF: ALL
I15	8150 lm	B03	5700K 3-step	9	CRI90		
I20	8200 lm	C03	5000K 3-step				
I20	8200 lm	E03	4000K 3-step				
I02	8020 lm	F03	3500K 3-step				
H75	7750 lm	G03	3000K 3-step				
H57	7570 lm	H03	2700K 3-step				
G76	6760 lm						
G76	6760 lm						
G99	6990 lm						
G99	6990 lm						
G76	6760 lm						
G50	6500 lm						
G41	6410 lm						


# Marking Information

## Marking Point



Marking point

## QR Code Information



4000K

8200lm

YYMMDD

100001

①

②

	QR Code Information							
Items	Factory	SAP Code	SMT Date	Rank Information	Line No.	Lot No.	Product	Notes
Digits	1 Digit	7 Digit	6 Digit	10 Digit	1 Digit	1 Digit	5 Digit	In Total 31 Digits
Information	*	*****	YYMMDD D	I20E03 8ALL <sup>(1)</sup>	1~9, A~Z	1~9, A~Z	00001	

## Plain Code Information

No.	Item	Information	Digits	Remark
①	CCT	4000K	5Digit	Refer to Page4
	Date	YYMMDD	6Digit	SMT date
②	Flux	8200lm	6Digit	Refer to Page4
	Lot No.	1	1 Digit	0~9,A~Z
	Sequence No.	00001	5 Digit	00001 ~ 99999

## Notes :

(1) Module Flux code rule as below table

Symbol	lm	Symbol	lm	Symbol	lm	Symbol	lm
D91	3910	O50	14500	R50	17500	U50	20500
M20	12200	P50	15500	S50	18500	V20	21200
N00	13000	Q50	16500	T50	19500	W00	22000

## Label Information

(K)PO Number	XXXXXX IIII II IIII III
(1P)Supplier P/N	SMJD-4845128C-G5N100I20E038ALL <sup>(1)</sup> IIII II IIII III
(33P)Bin Code	I20E038ALL <sup>(2)</sup> IIII II IIII III
(Q)Quantity	XX IIII II IIII III
(4L)Country of Origin	XX <sup>(3)</sup> IIII II IIII III
(10D)Date Code	YYWW <sup>(4)</sup> IIII II IIII III
(1T)Lot Code	YYMDDXXXXX- XXXXXXXX <sup>(5)</sup> IIII II IIII III

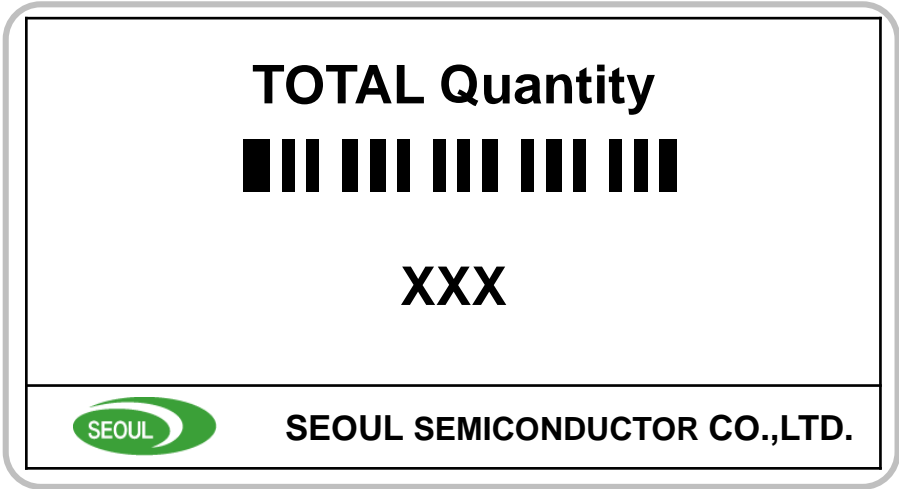

**SEOUL SEMICONDUCTOR CO.,LTD.**

### Notes

- (1) Please refer to SPEC page 20 (30 digit code)
- (2) Please refer to SPEC page 21
- (3) Country of Origin: 2 digit code . For example : Chinese Code: CN
- (4) Date Code : YYWW : Packing Date: Year + Week
- (5) Lot Code :  
 Initial of manufacture is refer to the 2D code rule.  
 YYMDD : Packing Date (Oct. : A, Nov. : B, Dec. : C)  
 X : Initial of Manufacturer  
 XXXX : Sealing Pack No.  
 XXXXXXXX : SSC SAP Code
- (6) Please refer to the font and size requirement for the label  
**the label must be clear , visible and scannable**
- (7) It is attached to the top left corner of the box.

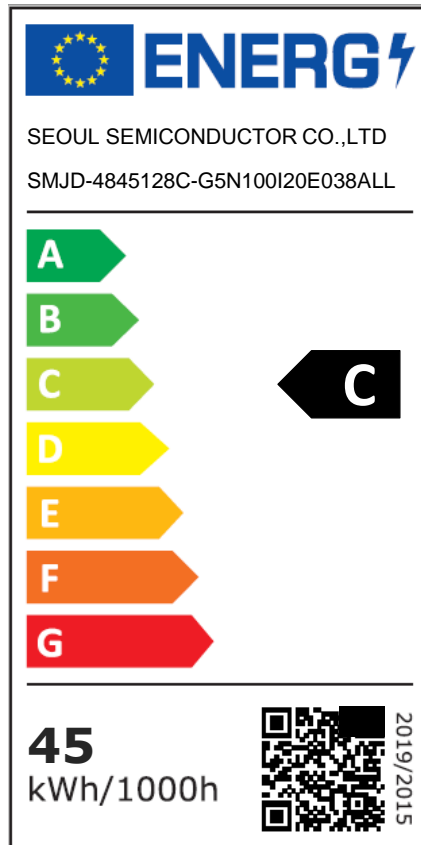
Code 128	Length mm	Height	Font	Size
PO Number	0.17 mm	3.0mm	Arial	7
Supplier	0.17 mm	3.0mm	Arial	7
Bin Code	0.17 mm	3.0mm	Arial	7
Qty	0.17 mm	3.0mm	Arial	7
Country of Origin	0.17 mm	3.0mm	Arial	7
Date Code	0.17 mm	3.0mm	Arial	7
Lot Code	0.17 mm	3.0mm	Arial	7
White space(TOP)	2-4mm			
White space(Under)	17mm			
White space(Left)	2-4mm			
End Left Text ~ Start Barcode	5-10mm			
Text Width(PGM)	100%			
Spacing	0%			
Company Text			Arial	9.5
Logo	Width 22-16mm	9-6mm		
Label size	100mm	70mm		

Label Information



- Notes**  
(1) It is attached to the bottom right corner of the box.

## Label Information

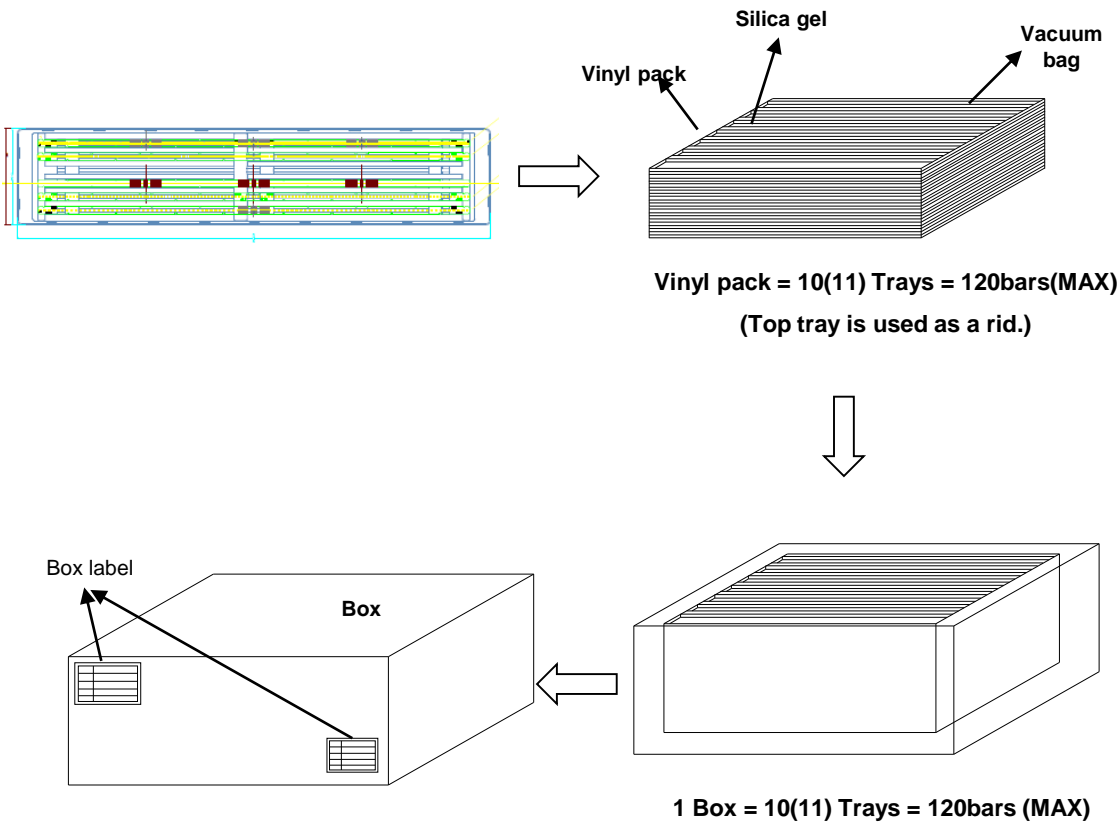


### Notes

- (1) The above is just an example, and the correct label must be downloaded from EPREL system
- (2) The label size should be 72mm\*36mm
- (3) The background of the label shall be 100% white.
- (4) The typefaces shall be Verdana and Calibri.
- (5) Colours shall be CMYK – cyan, magenta, yellow and black, following this example: 0-70-100-0: 0 % cyan, 70 % magenta, 100 % yellow, 0 % black.
- (6) It is attached to the top right corner of the box.

# Packaging Specification

Model	Tray		Box		Pallet	
	Size (mm)	Q'ty per tray (ea)	Size (mm)	Q'ty per box (ea)	Saze (mm)	Q'ty per pallet(ea)
SMJD-4845128C-G5N100	1229x249x23	12	1249x269x225	120	1100*1300*150	2160



## Precaution for Use

- (1) Check the appearance of module before wiring/ assembly, DO NOT use the LED cracked or PCB damaged module.
- (2) The module was designed to be driven with DC source, recognize the polarities of the module was necessity.
- (3) It was SELV module, DO NOT connect the LED directly to main power during wiring.
- (4) DO NOT let the LED packages contacted with any hard matters.
- (5) There was no current regulator built in module, unevenly load between different parallel modules may occur due to the modules  $V_F$  variance .
- (6) Please do not use together with the materials containing Sulfur.
- (7) Please do not make any modification on module.

## Precaution for Use

(8) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.

### a. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event:

One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls

- Humidity control (ESD gets worse in a dry environment)

### b. EOS (Electrical Over Stress)

Electrical Over-Stress (EOS) is defined as damage that may occur when an electronic device is subjected to a current or voltage that is beyond the maximum specification limits of the device.

The effects from an EOS event can be noticed through product performance like:

Changes to the performance of the LED package (If the damage is around the bond pad area and since the package is completely encapsulated the package may turn on but flicker show severe performance degradation.)

Changes to the light output of the luminaire from component failure

Components on the board not operating at determined drive power

Failure of performance from entire fixture due to changes in circuit voltage and current across total circuit causing trickle down failures

It is impossible to predict the failure mode of every LED exposed to electrical overstress as the failure modes have been investigated to vary, but there are some common signs that will indicate an EOS event has occurred.

- Damaged may be noticed to the bond wires (appearing similar to a blown fuse).
- Damage to the bond pads located on the emission surface of the LED package (shadowing can be noticed around the bond pads while viewing through a microscope).
- Anomalies noticed in the encapsulation and phosphor around the bond wires.
- This damage usually appears due to the thermal stress produced during the EOS event.

### c. To help minimize the damage from an EOS event Seoul Semiconductor recommends utilizing

- qualified LED driver with no big over shoot out put
- Isolated driver that to prevent harmful peaks passed to module.
- A current limiting device

## Storage before use

- (1) Do not impact or place pressure on this product because even a small amount of pressure can damage the product. The product should also not be placed in high temperatures, high humidity or direct sunlight since the device is sensitive to these conditions.
- (2) When storing devices for a long period of time before usage, please following these guidelines:
  - \* The devices should be stored in the anti-static bag that it was shipped in from Seoul-Semiconductor with opening.
  - \* If the anti-static bag has been opened, re-seal preventing air and moisture from being present in the bag.

## **Guidelines for properly working with Module**

- (1) Discharge the lighting system a minimum of 2-3 times prior to working with the module.
- (2) Use only properly rated test equipment and tools for the rated voltage and current of the product being tested.
- (3) It is strongly suggested to wear rubber insulated gloves and rubber bottom shoes.
- (4) Do not wear any conductive items (such as jewelry) which could accidentally contact electric circuits.
- (5) Perform several tests with power off and the lighting system unplugged.
- (6) Faults, lightning, or switching transients can cause voltage surges in excess of the normal ratings.
- (7) Internal component failure can cause excessive voltages.
- (8) Stored or residual electricity in long wire could be hazardous.
- (9) Make sure proper discharge prior to starting work.

## Company Information

### **Published by**

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### **Company Information**

Seoul Semiconductor (SeoulSemicon.com) manufactures and packages a wide selection of light emitting diodes (LEDs) for the automotive, general illumination/lighting, appliance, signage and back lighting markets. The company is the world's fifth largest LED supplier, holding more than 10,000 patents globally, while offering a wide range of LED technology and production capacity in areas such as "nPola", deep UV LEDs, "Acrich", the world's first commercially produced AC LED, and "Acrich MJT - Multi-Junction Technology" a proprietary family of high-voltage LEDs. The company's broad product portfolio includes a wide array of package and device choices such as Acrich, high-brightness LEDs, mid-power LEDs, side-view LEDs, through-hole type LED lamps, custom displays, and sensors. The company is vertically integrated from epitaxial growth and chip manufacture in it's fully owned subsidiary, Seoul Viosys, through packaged LEDs and LED modules in three Seoul Semiconductor manufacturing facilities. Seoul Viosys also manufactures a wide range of unique deep-UV wavelength devices.

### **Legal Disclaimer**

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## Revision History

Revision	Date	Page	Remarks
Rev0.1	2024-08-30	All	Preliminary data sheet for SMJD-4845128C-G5N100
Rev0.2	2024-09-24	1,16	Add "cuttable module" and update mechanical drawing
Rev0.3	2024-09-30	2,5	Add Ra90 parameters
Rev0.4	2024-12-25	All	Add UL related information and update the related photos and packing information, and CIE coordinate